

Rosin Flux

835 is a rosin-based liquid flux with moderate activity. This rosin flux is composed of pure Water White (WW) grade gum rosin in a unique solvent system, combined with highly effective activators. Post-soldering residues from this RA liquid flux are non-conductive, non-corrosive, hygroscopic, non-tacky, and fungus resistant.

This rosin soldering flux can be used in both automated and manual soldering applications. It is great for general purpose soldering of PCBs, wire, cable, and semiconductors. It is also ideal for solder coating or tinning leads. It may be applied by spray, or foam for wave soldering applications.



Features & Benefits

- Meets IPC J-STD-004B and type ROM1
- For both leaded and lead-free solders
- Fast wetting
- Excellent foaming
- RoHS-compliant

Available Packaging

Cat. No.	Packaging	Net Vol.	Net Wt.
835-100ML	Bottle	125 mL	116 g
835-100MLCA	Bottle	125 mL	116 g
835-1L	Bottle	1 L	930 g

Contact Information

MG Chemicals, 1210 Corporate Drive
Burlington, Ontario, Canada L7L 5R6

Email: support@mgchemicals.com

Phone: North America: +(1)800-340-0772

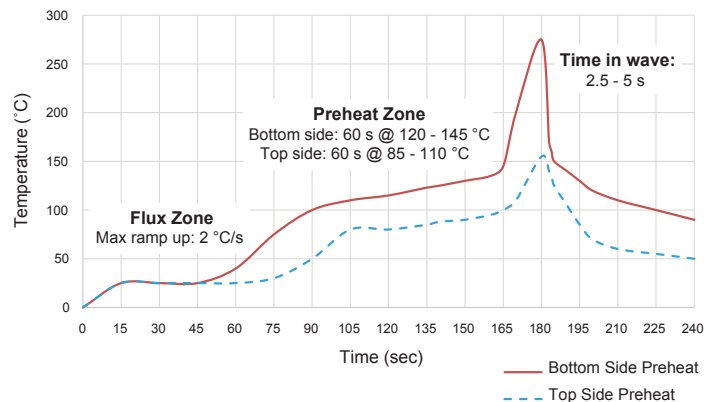
International: +(1) 905-331-1396

Europe: +(44)1663 362888

Properties

Flux Classification	ROM1 RA
Flux Type	Rosin
Flux Activity	Moderate
Copper Mirror	Partial removal
Corrosion Test	Pass
Cleaning Requirements	Recommended
Halides (by weight)	0.44 %

Typical Lead-Free Wave Solder Profile



Application Instructions

Read the product SDS before using this product (downloadable at www.mgchemicals.com).

1. Apply flux on the surface by dip, spray, foam, or brush application.
2. Clean residue with MG 413B, 413C, 4140, 4050A, or 4140A flux removers.

Wave Solder Operating Parameters

Amount of Flux:

Foam	1000–2000 µg/in ² solids
Spray	750–1500 µg/in ² solids

Foam Fluxing Parameters:

Foam Stone Pore Size	20–50 µm
Flux Level Above Stone	25–40 mm
Chimney Opening	10–13 mm
Air Pressure	1–2 lb/in ²

Top Side Preheat Temp. 85–110 °C

Bottom Side Preheat Temp. 35 °C

Conveyor-speed 1.2–2.8 m/min

Contact Time in Solder 2.5–4.5 s

Solder Pot Temp.

Sn96.5/Ag3.5	260–276 °C
Sn95/Ag5	280–296 °C
Sn99.3/Cu0.7	265–276 °C
SnAgCu	271–276 °C
Sn95/Sb5	280–296 °C

Foam Flux

- The foam fluxer should be provided with the compressed air
- Flux tank must be always full
- Surface of the flux should be 0.5–1" above the top of the flux aerator or flux stone
- Adjust pressure to optimize foam height with a fine uniform foam head
- After fluxing, use an air knife to remove excess flux from the machine

To check for uniformity of spray flux coating, run a tempered glass plate provided by the machine manufacturer through the flux and preheat zones. Ensure to inspect the glass before the wave zone.

Storage and Handling

Store between 18 and 27 °C in a dry area, away from sunlight (see SDS).

Disclaimer

This information is believed to be accurate. It is intended for professional end-users who have the skills required to evaluate and use the data properly. M.G. Chemicals Ltd. does not guarantee the accuracy of the data and assumes no liability in connection with damages incurred while using it.